

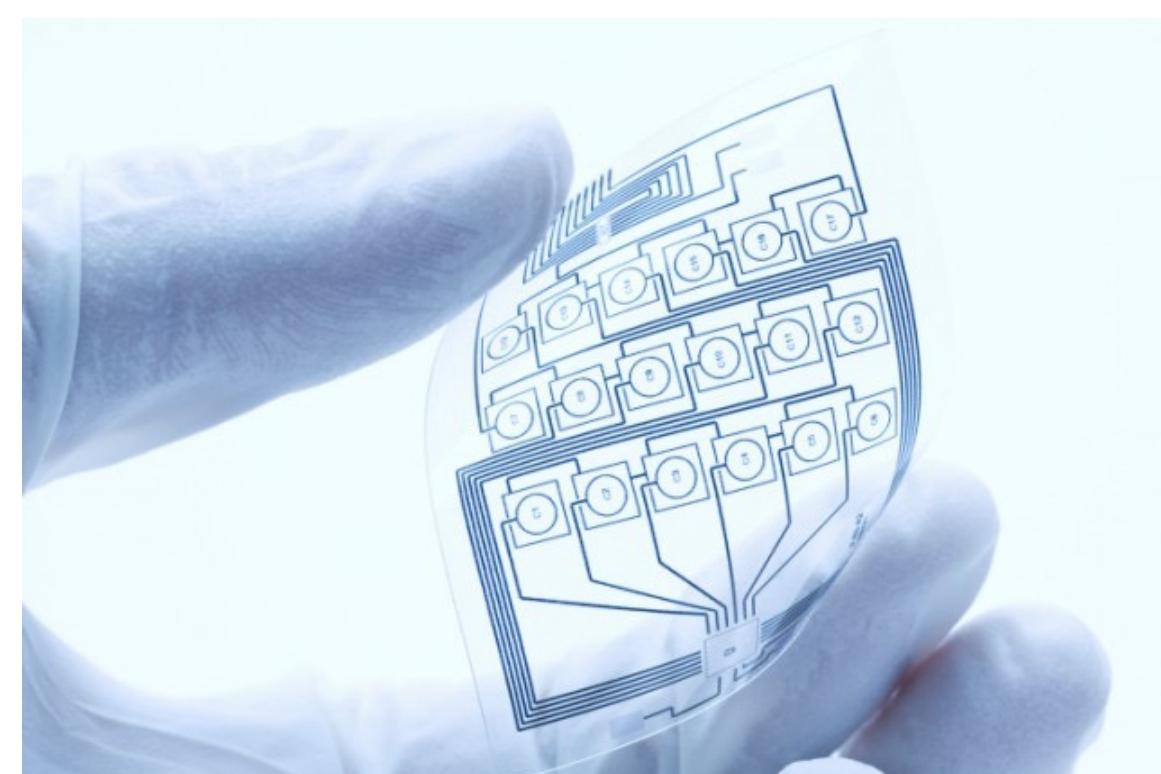


Varun Varanasi, Abolfalzl Kiani, and Michael Dickey

Department of Chemical & Biomolecular Engineering, North Carolina State University

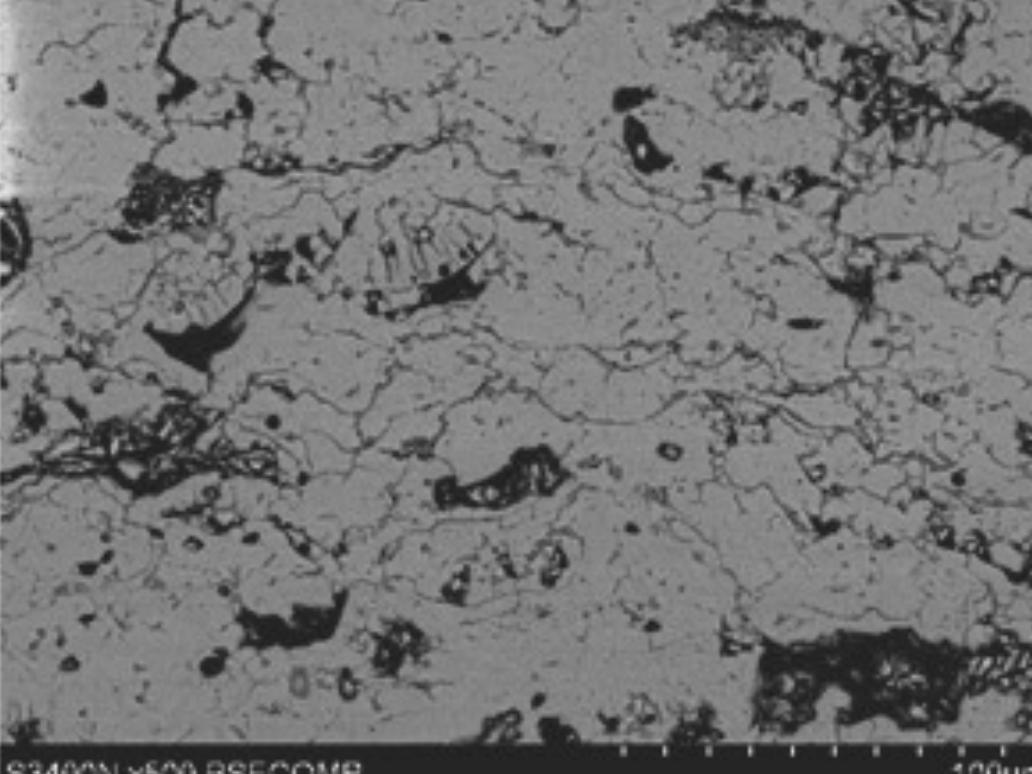
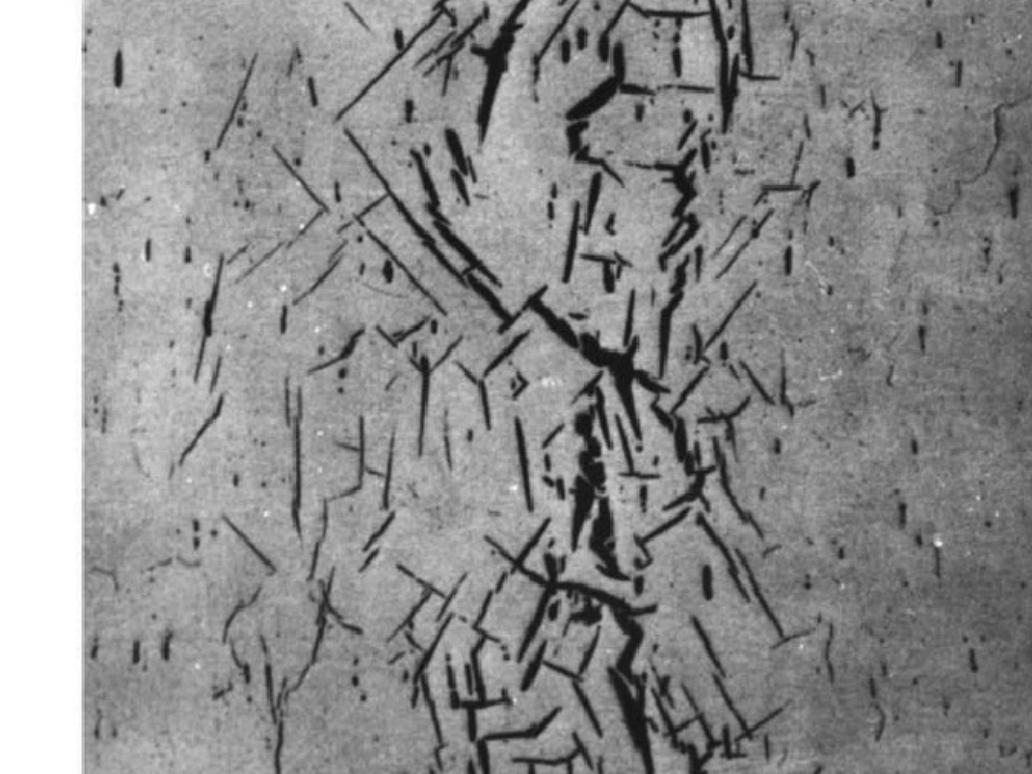
Introduction

Flexible Electronics

www.mddionline.com/how-make-flexible-electronics-stickarstechnica.com/science/2012/06/bend-me-shape-me-flexible-electronics-perform-under-punishing-conditions/

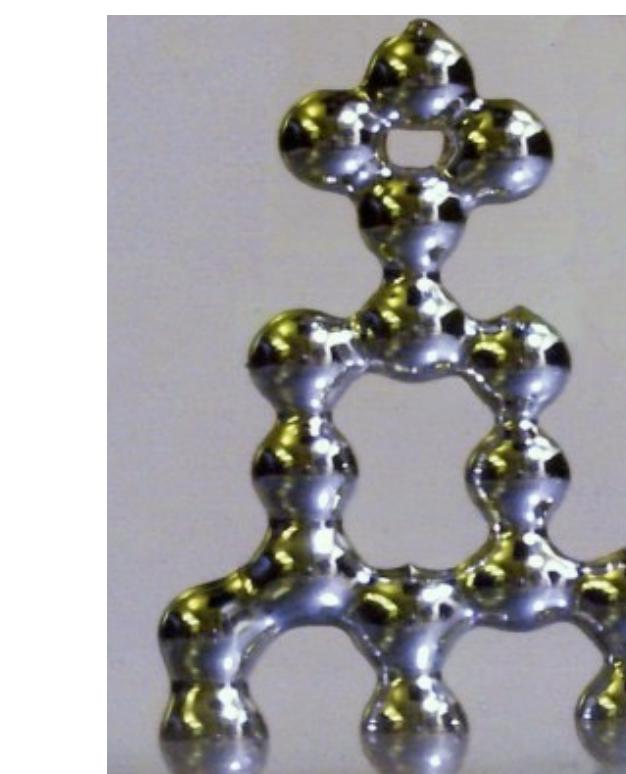
- With time and use flexible electronics begin to degrade forming microcracks

Microcracks

Glema et al, *International Journal of Damage Mechanics* (2010)Moskal et al, *Defect and Diffusion Forum* (2011)

- Microcracks reduce conductivity and efficiency eventually deteriorating the entire device itself

EGaIn

Ladd et al, *Advanced Materials*, (2013)Chiechi et a, *Chem. Int. Ed.* (2008)

- Melting point near 16 C
- Thin oxide layer
- Removed by electrochemical reduction or Acid-Base reaction

Alternative Deposition Methods



Physical Placement

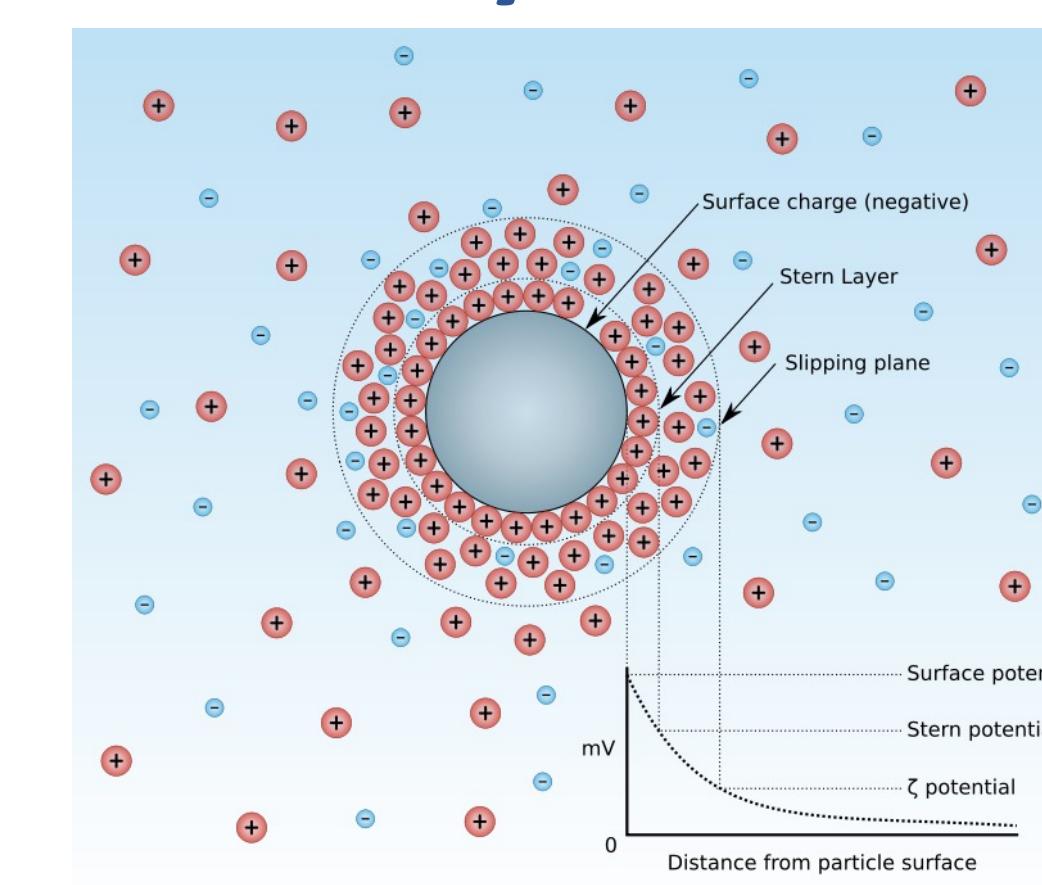


Dry Deposition

Nanoparticle Solution Synthesis

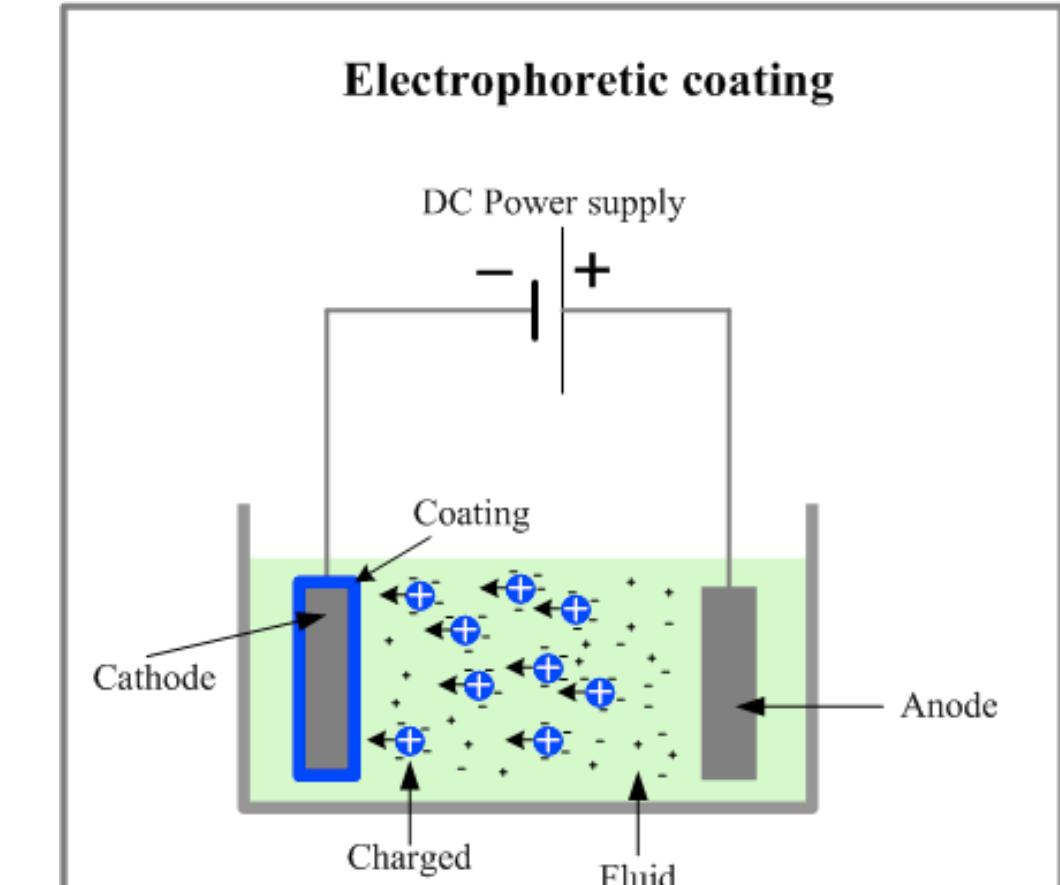


EGaIn nanoparticle solution



Surface Charge

Electrophoretic Deposition



www.subtech.com/dokuwiki/doku.php?id=electrophoretic_deposition



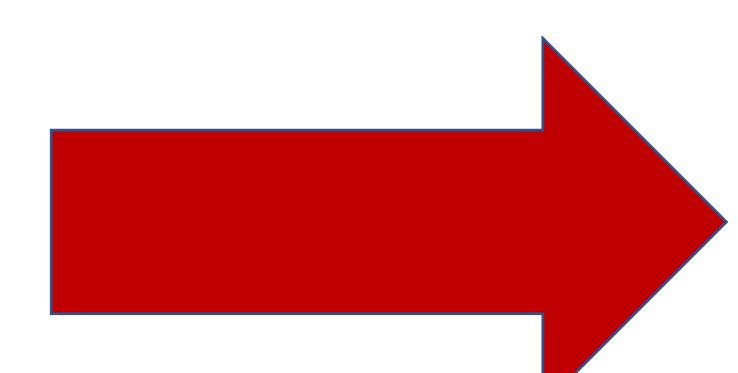
EPD Setup

EGaIn EPD

EGaIn Electrophoretic Deposition



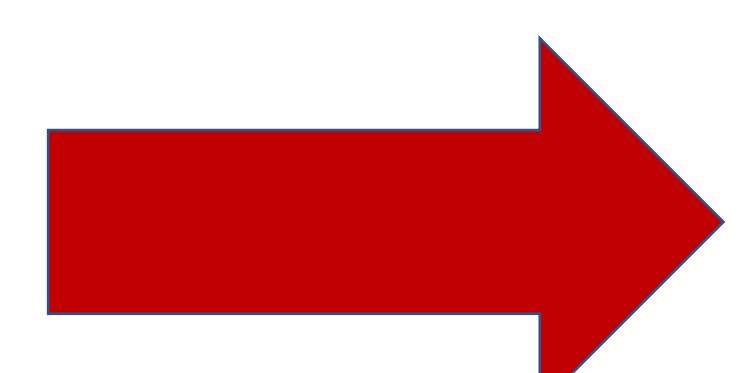
Wet EGaIn EPD



Dry EGaIn EPD

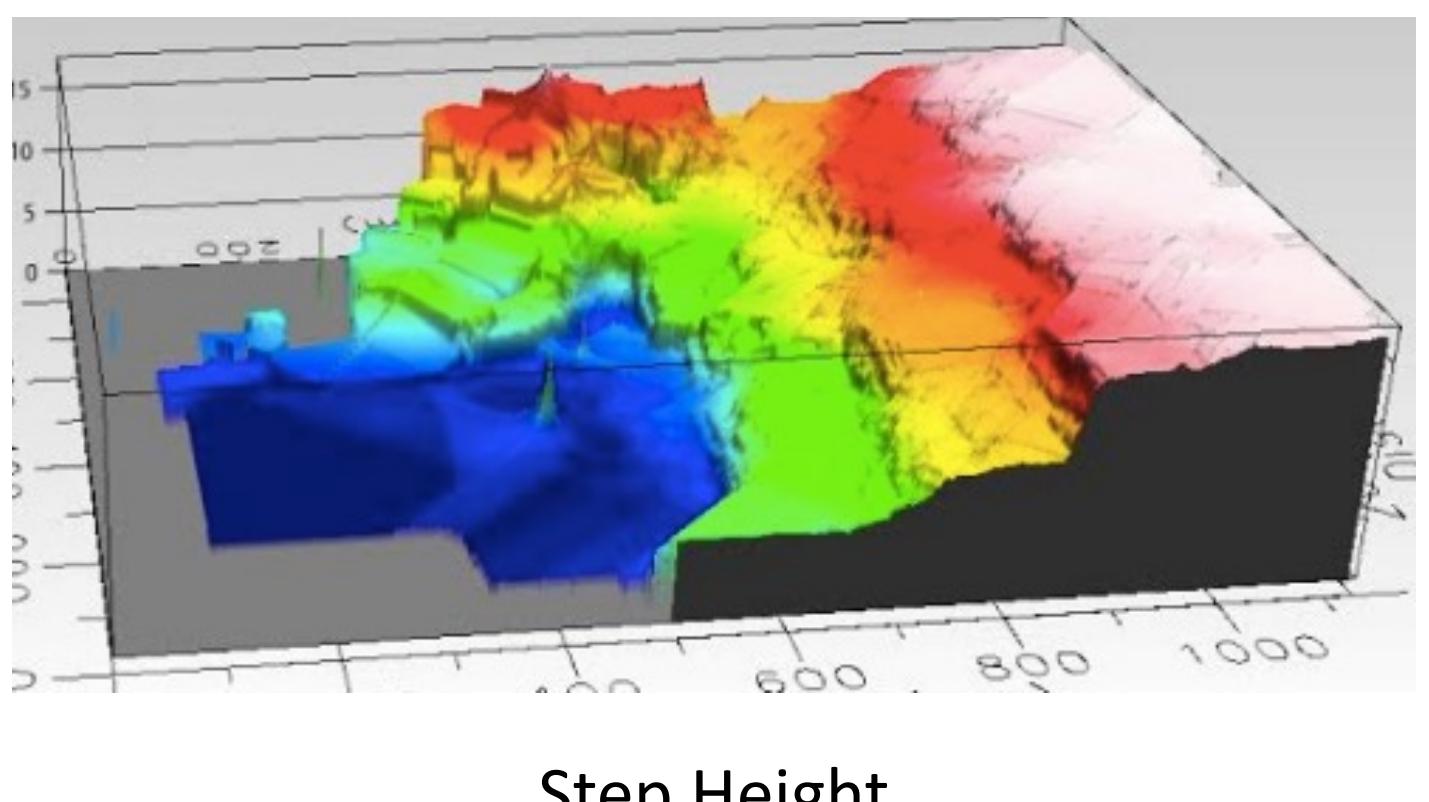


Acid Wash

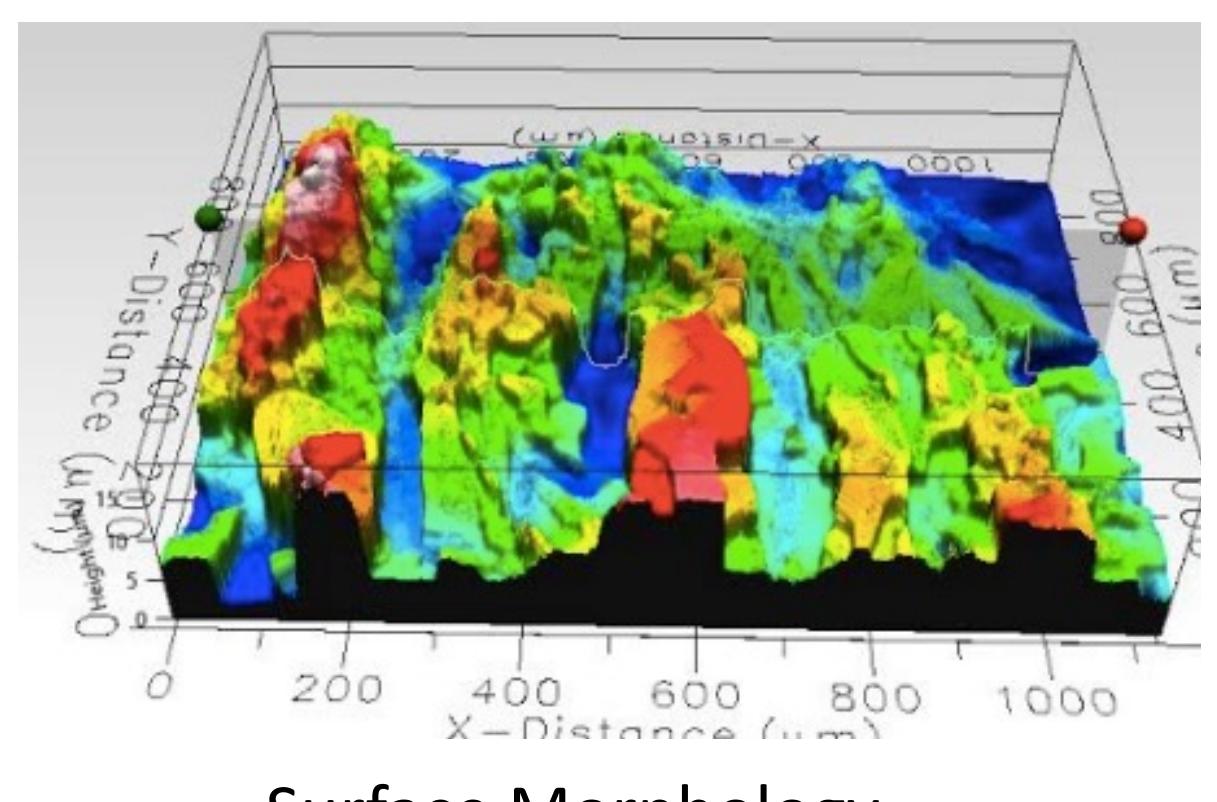


Liquid Metal Thin Film

Surface Morphology Characterization



Step Height



Surface Morphology

Measurements

Average Height: 11.46 μm
 Maximum Height: 17.51 μm
 Minimum Height: 0.9695 μm
 Step Height: 10-20 μm

- EPD is a viable method for EGaIn nanoparticle deposition
- EPD is optimized with an electric field 200-250 V/cm, charging salt concentration near 0.108M, and 0.03g/L EGaIn in IPA
- Charging salt is not necessary for deposition to occur, but is necessary for deposition to adhere strongly
- Thin Film thickness is directly correlated to EGaIn concentration charging salt concentration and duration of EPD
- HCl Acid wash is necessary for liquid thin film creation
- Ice Bath is not necessary for EGaIn deposition but does increase efficiency
- EPD efficiency decreases at temperatures that are too cold

Conclusion

Future Work

- Reduce film thickness
- Further Surface morphology characterization
- Decrease thin film surface roughness
- Find Ideal temperature for EPD
- Apply EGaIn EPD to circuits
- Maximize EPD Rate